

Taiwan Semiconductor

3000W, 12V- 47V Surface Mount Transient Voltage Suppressor

FEATURES

- AEC-Q101 qualified
- Moisture sensitivity level: level 1, per J-STD-020
- Meets IEC 61000-4-2 (Level: 4) / ISO 10605 (Level: L4)
- Meets ISO 7637-2 (Pulse 1/2a/2b/3a/3b)
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Motor for BLDC
- Lighting application
- Battery Management System
- Automotive

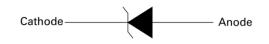
MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.210g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
V _{WM}	10 - 40	V		
V _{BR}	12 - 47	V		
P _{PPM}	3000	W		
T _{J MAX}	175 °C			
Polarity	Uni-directional			
Package	DO-214AB (SMC)			



DO-214AB (SMC)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)						
PARAMETER SYMBOL VALUE UN						
Non-repetitive peak impulse power dissipation with 10/1000µs waveform ⁽¹⁾	P _{PPM}	3000	W			
Steady state power dissipation at $T_L = 25^{\circ}C^{(2)}$	P _D	8.5	W			
Peak forward surge current 8.3ms single half sine-wave	I _{FSM}	300	А			
Junction temperature	TJ	-55 to +175	°C			
Storage temperature	T _{STG}	-55 to +175	°C			

Notes:

- 1. Non-repetitive current pulse per Fig.3 and derated above $T_A = 25^{\circ}C$ per Fig.1
- 2. Units mounted on PCB (16mm x 16mm Cu pad test board)



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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	ТҮР	UNIT		
Junction-to-lead thermal resistance	R _{ƏJL}	17	°C/W		
Junction-to-ambient thermal resistance	R _{eja}	50	°C/W		
Junction-to-case thermal resistance	R _{eJC}	10	°C/W		

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}C$ unless otherwise noted)											
		I _R max at V _{WM}		V_{BR} at $I_{T}^{(1)}$			V _C at I _{ΡΡΜ} 10 / 1000 μs		R _D 10 / 1000 μs	αT ⁽²⁾	
Part number	Marking code			Min	Тур	Max	Ι _τ	Мах			Мах
		μA	V	v		m	mA		A ⁽⁴⁾	Ω	10 ⁻⁴ /°C
3KSMC12AH	3K12A	5	10	11.4	12.0	12.6	1	17.0	176	0.028	7.8
3KSMC15AH	3K15A	3	13	14.3	15.0	15.8	1	21.5	140	0.046	8.4
3KSMC18AH	3K18A	3	15	16.7	17.6	18.5	1	24.4	123.0	0.055	8.8
3KSMC19AH	3K19A	3	16	17.8	18.7	19.6	1	26.0	115.4	0.063	8.8
3KSMC21AH	3K21A	3	18	20	21.1	22.2	1	29.2	102.7	0.079	9.2
3KSMC23AH	3K23A	3	20	22.2	23.4	24.6	1	32.4	92.6	0.097	9.4
3KSMC26AH	3K26A	3	22	24.4	25.7	27.0	1	35.5	84.5	0.116	9.6
3KSMC28AH	3K28A	3	24	26.7	28.1	29.5	1	38.9	77.1	0.140	9.6
3KSMC30AH	3K30A	3	26	28.9	30.4	31.9	1	42.1	71.3	0.164	9.7
3KSMC33AH	3K33A	3	28	31.1	32.7	34.3	1	45.4	66.1	0.192	9.8
3KSMC35AH	3K35A	3	30	33.3	35.1	36.9	1	48.4	62.0	0.215	9.9
3KSMC39AH	3K39A	3	33	36.7	38.6	40.5	1	53.3	56.3	0.261	10.0
3KSMC42AH	3K42A	3	36	40.0	42.1	44.2	1	58.1	48.4	0.331	10.0
3KSMC47AH	3K47A	3	40	44.4	46.7	49.0	1	64.5	43.5	0.409	10.1

Notes:

1. Pulse test: tp < 30ms

2. To calculate V_{BR} or V_C versus junction temperature, use following formulas: V_{BR} at $T_J = V_{BR}$ at 25°C x (1 + α T x (T_J-25))

 V_c at $T_j = V_c$ at 25°C x (1 + α T x (T_j-25))

3. To calculate maximum clamping voltage at other surge level, use the following formula: $V_{Cmax} = V_C - R_D x (I_{PP} - I_{PPappli})$ where $I_{PPappli}$ is the surge current in the application.

ORDERING INFORMATION				
ORDERING CODE PACKAGE PACKING				
3KSMCxAH	DO-214AB (SMC)	3,000 / Tape & Reel		

Notes:

1. "x" defines voltage from 12V (3KSMC12AH) to 47V (3KSMC47AH)



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CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

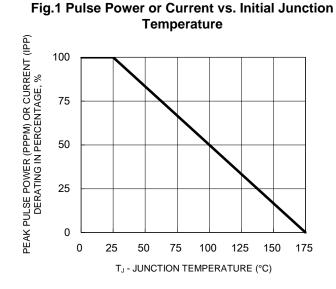


Fig.3 Clamping Power Pulse Waveform

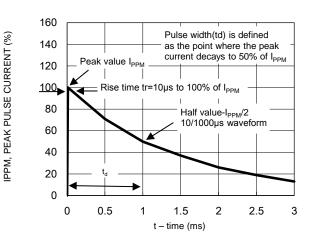
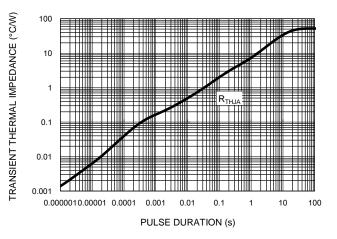


Fig.5 Typical Transient Thermal Impedance



P_D - POWER DISSIPATION (W) LEAD TEMPERATURE (°C)

Fig.4 Typical Junction Capacitance

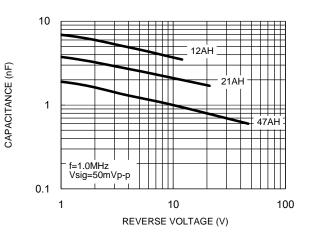


Fig.6 Peak Pulse Power Rating Cure

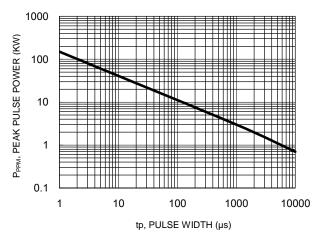


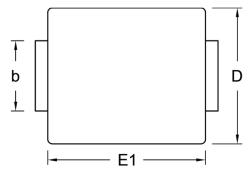
Fig.2 Steady State Power Derating

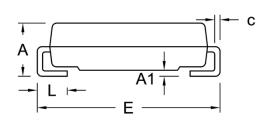


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PACKAGE OUTLINE DIMENSIONS

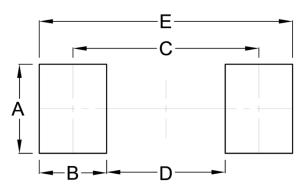






DIM.	Unit	(mm)	Unit (inch)		
	Min.	Max.	Min.	Max.	
A	2.00	2.62	0.079	0.103	
A1	-	0.20	-	0.008	
b	2.90	3.20	0.114	0.126	
с	0.15	0.31	0.006	0.012	
D	5.59	6.22	0.220	0.245	
E	7.75	8.13	0.305	0.320	
E1	6.60	7.11	0.260	0.280	
L	1.00	1.60	0.039	0.063	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

MARKING DIAGRAM



- P/N = Marking Code
- G = Green Compound
- YW = Date Code

F = Factory Code



3KSMC12AH – 3KSMC47AH

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